

ProLight PB2H-5MVE-HWFCRxAxx 5W High CRI Power LED Technical Datasheet Version: 1.0

ProLight Opto PB2H Series

Features

- · Corrosion robustness
- · SMD 3535 ceramic package
- · Maximum drive current: 1500 mA
- · Viewing angle: 110° (Lambertian optical lens)
- · Best JEDEC Moisture Sensitivity Level 1

Main Applications

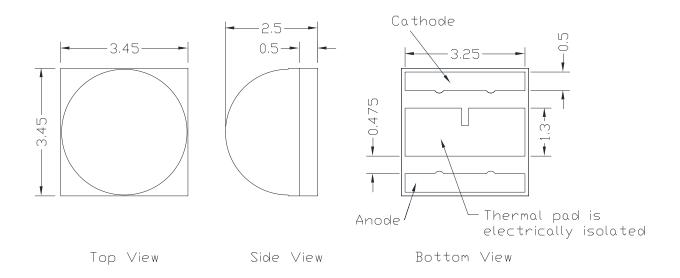
- · Entertainment Lighting
- · Commercial Lighting
- · Indoor Lighting
- · Outdoor Lighting

Introduction

•Phenix 3535 qualifies as the JEDEC Level 1 MSL sensitivity level and suitable for SMD process, Pb_free reflow soldering capability, and full compliance with EU Reduction of Hazardous Substances (RoHS) legislation.



Emitter Mechanical Dimensions





Notes:

- 1. Drawing not to scale.
- 2. All dimensions are in millimeters.
- 3. Unless otherwise indicated, tolerances are \pm 0.1mm.
- 4. Please do not solder the emitter by manual hand soldering, otherwise it will damage the emitter.
- 5. Please do not use a force of over 0.3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

^{*}The appearance and specifications of the product may be modified for improvement without notice.



Flux Characteristics, $T_j = 25^{\circ}C$

| | Luminous Flu | minous Flux Φ _V (lm) | | | | |
|------------------------|--------------|---------------------------------|-----------------|------------------|------------------|-------------|
| Part Number Emitter | @35 | i0mA | Refer @700mA | Refer @1000mA | Refer @1500mA | CRI Min. |
| | Min. | Тур. | Тур. | Тур. | Тур. | |
| PB2H-5MVE-HWFCR8A24 | 140 | 155 | 289 | 394 | 541 | 80 |
| PB2H-5MVE-HWFCR8A21 | 120 | 128 | 240 | 325 | 447 | 80 |
| PB2H-5MVE-HWFCR9A24 | 100 | 110 | 206 | 280 | 384 | 90 |
| PB2H-5MVE-HWFCR9A21 | 90 | 105 | 197 | 267 | 369 | 90 |

- ProLight maintains a tolerance of ± 7% on flux and power measurements.
- ProLight maintains a tolerance of ± 2 on CRI measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

Electrical Characteristics, T₁ = 25°C

| Forward Voltage V _F (V) | | | | | | Thermal | |
|------------------------------------|------|--------|------|-----------------|------------------|------------------|---------------------------|
| | | @350mA | | Refer @700mA | Refer @1000mA | Refer @1500mA | Resistance Junction to |
| Color | Min. | Тур. | Max. | Тур. | Тур. | Тур. | Slug (°C/W) |
| Warm White | 2.60 | 2.80 | 3.00 | 2.90 | 3.00 | 3.33 | 4.9 |

ullet ProLight maintains a tolerance of \pm 0.1V for Voltage measurements.

Optical Characteristics at 350mA, $T_1 = 25^{\circ}C$

| Color | Bin Code | Colo | сст | Viewing Angle (degrees) | |
|------------|-----------|--------|--------|-------------------------------|--------------------|
| Color | Bill Code | Min. | Тур. | Max. | 2 θ _{1/2} |
| Marm Mhita | LO | 2380 K | 2400 K | 2510 K | 110 |
| Warm White | K0 | 2090 K | 2100 K | 2190 K | 110 |

ProLight maintains a tolerance of ± 5% for CCT measurements.



Electro-Optical Characteristics, T_J = 25°C

| I _F (mA) | V _F (V) | Power (W) | PB2H-5MVE-HWFCR8A24 Flux (lm) | PB2H-5MVE-HWFCR8A21 Flux (Im) |
|---------------------|----------------------|-----------------------|----------------------------------|----------------------------------|
| 350 | 2.80 | 0.98 | 155 | 128 |
| 500 | 2.83 | 1.42 | 215 | 176 |
| 700 | 2.90 | 2.03 | 289 | 240 |
| 1000 | 3.00 | 3.00 | 394 | 325 |
| 1200 | 3.05 | 3.66 | 458 | 376 |
| 1500 | 3.33 | 5.00 | 541 | 447 |
| | | | | |
| I _F (mA) | V _F (V) | Power (W) | PB2H-5MVE-HWFCR9A24 Flux (lm) | PB2H-5MVE-HWFCR9A21 Flux (lm) |
| I _F (mA) | V _F (V) | Power (W) 0.98 | | |
| | | , , | Flux (lm) | Flux (lm) |
| 350 | 2.80 | 0.98 | Flux (lm) 110 | Flux (lm) 105 |
| 350 500 | 2.80 2.83 | 0.98 1.42 | Flux (lm) 110 152 | Flux (lm) 105 146 |
| 350 500 700 | 2.80 2.83 2.90 | 0.98 1.42 2.03 | Flux (lm) 110 152 206 | Flux (Im) 105 146 197 |

All values are reference only.

Absolute Maximum Ratings

| Parameter | Warm White | | |
|--|---|--|--|
| DC Forward Current (mA) | 1500 | | |
| Peak Pulsed Forward Current (mA) | 2000 (less than 1/10 duty cycle@1KHz) | | |
| ESD Sensitivity (HBM per MIL-STD-883E Method 3015.7) | 2KV | | |
| LED Junction Temperature | 150°C | | |
| Operating Temperature | -40°C - 105°C | | |
| Storage Temperature | -40°C - 120°C | | |
| Soldering Temperature | JEDEC 020c 260°C | | |
| Allowable Reflow Cycles | 3 | | |
| Reverse Voltage | Not designed to be driven in reverse bias | | |



Photometric Luminous Flux Bin Structure at 350mA

| Color | Bin Code | Minimum Photometric Flux (Im) | Maximum Photometric Flux (Im) | Available Color Bins |
|-----------------------|-------------|----------------------------------|----------------------------------|-------------------------|
| | W2 | 140 | 155 | All [1] |
| PB2H-5MVE-HWFCR8A24 | X1 | 155 | 170 | |
| | X2 | 170 | 185 | [1] |
| | Y1 | 185 | 200 | [1] |
| | V2 | 120 | 130 | All |
| | W1 | 130 | 140 | [1] |
| PB2H-5MVE-HWFCR8A21 | W2 | 140 | 155 | [1] |
| | X1 | 155 | 170 | [1] |
| | U2 | 100 | 110 | All |
| DDOLL FMVE LIMEDDOAGA | V1 | 110 | 120 | [1] |
| PB2H-5MVE-HWFCR9A24 | V2 | 120 | 130 | [1] |
| | W1 | 130 | 140 | [1] |
| | U1 | 90 | 100 | All |
| | U2 | 100 | 110 | [1] |
| PB2H-5MVE-HWFCR9A21 | V1 | 110 | 120 | [1] |
| | V2 | 120 | 130 | [1] |

- ProLight maintains a tolerance of \pm 7% on flux and power measurements.
- The flux bin of the product may be modified for improvement without notice.
- [1] The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.

Forward Voltage Bin Structure at 350mA

| Color | Bin Code | Minimum Voltage (V) | Maximum Voltage (V) |
|------------|-------------|---------------------|---------------------|
| Warm White | A | 2.6 | 2.8 |
| | B | 2.8 | 3.0 |

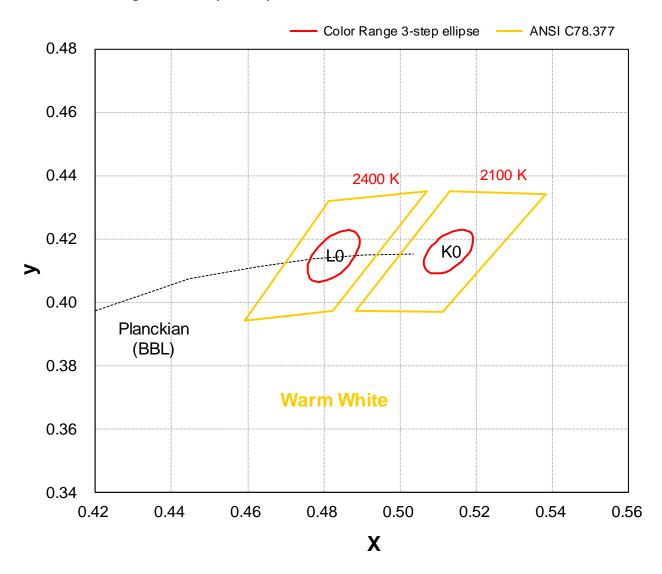
ProLight maintains a tolerance of ± 0.1V for Voltage measurements.

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.



Color Bin

Warm White Binning Structure Graphical Representation



Warm White Bin Structure

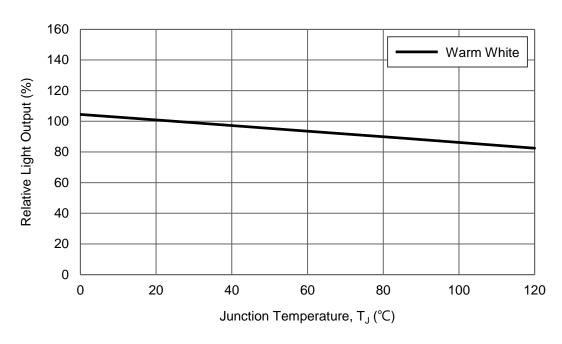
| Bin Code | Center | Oval parameter | Typ. CCT (K) | Bin Code | Center | Oval parameter | Typ. CCT (K) |
|----------|------------------|----------------------------------|-----------------|----------|------------------|--|-----------------|
| K0 x | 0.5128 0.4160 | a 0.0083 b 0.0046 ө° 48.65 | 2100 | LO x | 0.4825 0.4147 | a 0.0095 b 0.0049 Θ° 53.70 | 2400 |

- Color range stay within MacAdam "3-step" ellipse from the chromaticity center.
- The chromaticity center refers to ANSI C78.377.
- Tolerance on each color bin (x, y) is ± 0.005



Light Output Characteristics

Relative Light Output vs. Junction Temperature at 1500mA



Forward Current Characteristics, T_j = 25°C

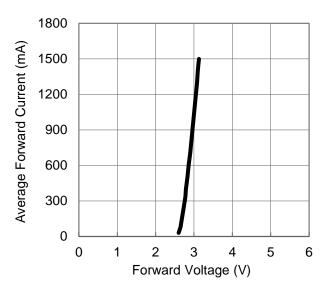


Fig 1. Forward Current vs. Forward Voltage for Warm White.

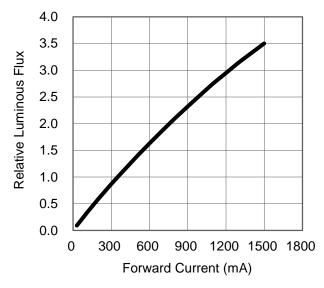
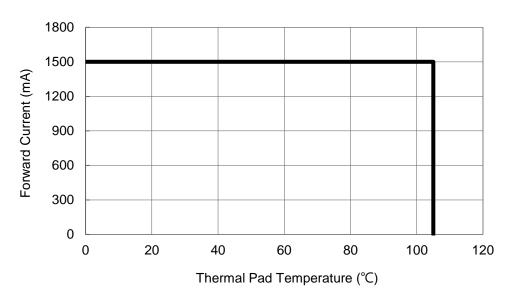


Fig 2. Relative Luminous Flux vs. Forward Current for Warm White at T_{.i}=25 maintained.

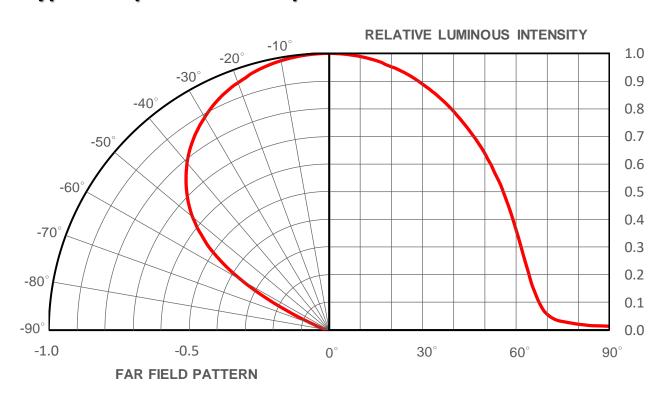


Thermal Pad Temperature vs. Maximum Forward Current

1. Warm White



Typical Representative Spatial Radiation Pattern



2025/02 DS-1968



Moisture Sensitivity Level - JEDEC Level 1

| | | | Soak Requirements | | | |
|-------|------------|-------------------|-------------------|------------------|-------------------------|------------|
| Level | Floor Life | | Standard | | Accelerated Environment | |
| | Time | Conditions | Time (hours) | Conditions | Time (hours) | Conditions |
| 1 | Unlimited | ≤30°C / 85% RH | 168 +5/-0 | 85°C / 85% RH | NA | NA |

- The standard soak time includes a default value of 24 hours for semiconductor manufature's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

| | | | | Soak Req | uirements | |
|-------|------------------------|-------------------|------------------------|------------------|-------------------------|------------------|
| Level | Floor | r Life | Stan | dard | Accelerated Environment | |
| | Time | Conditions | Time (hours) | Conditions | Time (hours) | Conditions |
| 1 | Unlimited | ≤30°C / 85% RH | 168 +5/-0 | 85°C / 85% RH | NA | NA |
| 2 | 1 year | ≤30°C / 60% RH | 168 +5/-0 | 85°C / 60% RH | NA | NA |
| 2a | 4 weeks | ≤30°C / 60% RH | 696 +5/-0 | 30°C / 60% RH | 120 +1/-0 | 60°C / 60% RH |
| 3 | 168 hours | ≤30°C / 60% RH | 192 +5/-0 | 30°C / 60% RH | 40 +1/-0 | 60°C / 60% RH |
| 4 | 72 hours | ≤30°C / 60% RH | 96 +2/-0 | 30°C / 60% RH | 20 +0.5/-0 | 60°C / 60% RH |
| 5 | 48 hours | ≤30°C / 60% RH | 72 +2/-0 | 30°C / 60% RH | 15 +0.5/-0 | 60°C / 60% RH |
| 5a | 24 hours | ≤30°C / 60% RH | 48 +2/-0 | 30°C / 60% RH | 10 +0.5/-0 | 60°C / 60% RH |
| 6 | Time on Label (TOL) | ≤30°C / 60% RH | Time on Label (TOL) | 30°C / 60% RH | NA | NA |



Qualification Reliability Testing

| Stress Test | Stress Conditions | Stress Duration | Failure Criteria |
|--|--|--------------------|-------------------------|
| Room Temperature Operating Life (RTOL) | 25°C, I _F = max DC (Note 1) | 1000 hours | Note 2 |
| Wet High Temperature Operating Life (WHTOL) | 85° C/60%RH, I _F = max DC (Note 1) | 1000 hours | Note 2 |
| Wet High Temperature Storage Life (WHTSL) | 85°C/85%RH, non-operating | 1000 hours | Note 2 |
| High Temperature Storage Life (HTSL) | 110°C, non-operating | 1000 hours | Note 2 |
| Low Temperature Storage Life (LTSL) | -40°C, non-operating | 1000 hours | Note 2 |
| Non-operating Temperature Cycle (TMCL) | -40°C to 120°C, 30 min. dwell, <5 min. transfer | 200 cycles | Note 2 |
| Mechanical Shock | 1500 G, 0.5 msec. pulse, 5 shocks each 6 axis | | Note 3 |
| Natural Drop | On concrete from 1.2 m, 3X | | Note 3 |
| Variable Vibration Frequency | 10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis | | Note 3 |
| Solder Heat Resistance (SHR) | 260°C ± 5°C, 10 sec. | | Note 3 |
| Solderability | Steam age for 16 hrs., then solder dip at 260°C for 5 sec. | | Solder coverage on lead |

Notes:

- 1. Depending on the maximum derating curve.
- 2. Criteria for judging failure

| Item | Test Condition | Criteria for Judgement | | |
|--|-------------------------|------------------------|---------------------|--|
| item | Test Condition | Min. | Max. | |
| Forward Voltage (V _F) | $I_F = max DC$ | | Initial Level x 1.1 | |
| Luminous Flux or Radiometric Power (Φ _V) | I _F = max DC | Initial Level x 0.7 | | |
| Reverse Current (I _R) | $V_R = 5V$ | | 50 µA | |

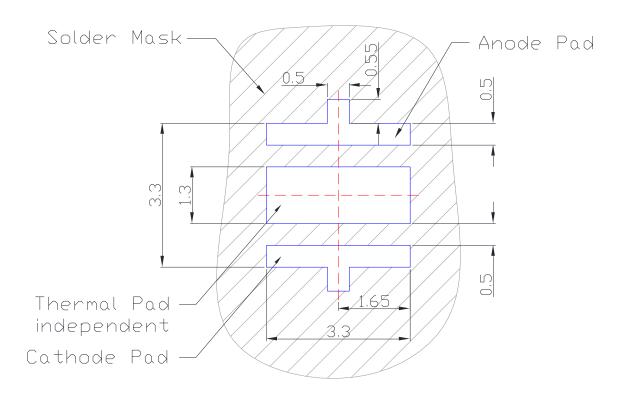
^{*} The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.



Recommended Solder Pad Design

Standard Emitter

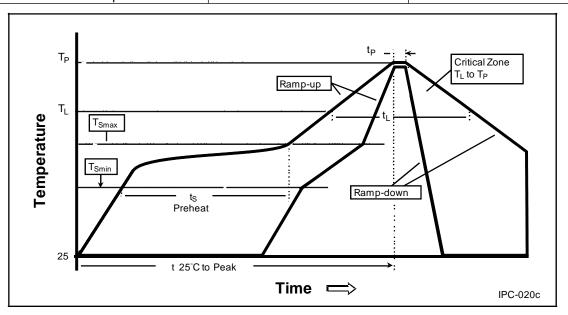


- All dimensions are in millimeters.
- Electrical isolation is required between Thermal Pad and Anode or Cathode Pad.



Reflow Soldering Condition

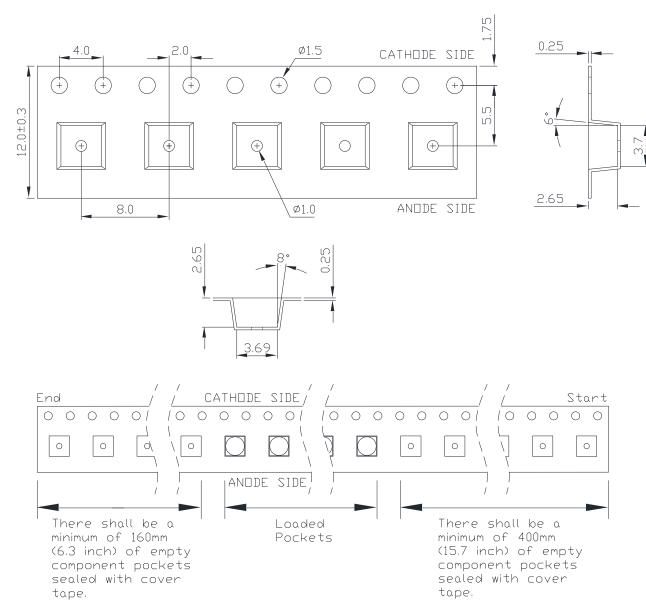
| Profile Feature | Sn-Pb Eutectic Assembly | Pb-Free Assembly |
|---|-------------------------|-------------------|
| Average Ramp-Up Rate | 3°C / second max. | 3°C / second max. |
| $(T_{Smax} \text{ to } T_{P})$ | | |
| Preheat | | |
| – Temperature Min (T _{Smin}) | 100°C | 150°C |
| – Temperature Max (T _{Smax}) | 150°C | 200°C |
| – Time (t _{Smin} to t _{Smax}) | 60-120 seconds | 60-180 seconds |
| Time maintained above: | | |
| – Temperature (T _L) | 183°C | 217°C |
| – Time (t _L) | 60-150 seconds | 60-150 seconds |
| Peak/Classification Temperature (T _P) | 240°C | 260°C |
| Time Within 5°C of Actual Peak | 10-30 seconds | 20-40 seconds |
| Temperature (t _p) | | |
| Ramp-Down Rate | 6°C/second max. | 6°C/second max. |
| Time 25°C to Peak Temperature | 6 minutes max. | 8 minutes max. |



- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a
 double-head soldering iron should be used. It should be confirmed beforehand whether the
 characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.



Emitter Reel Packaging

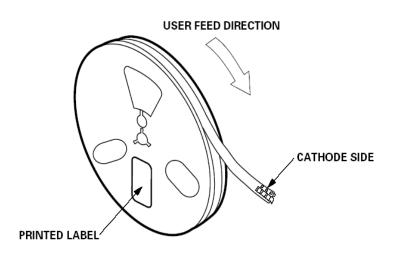


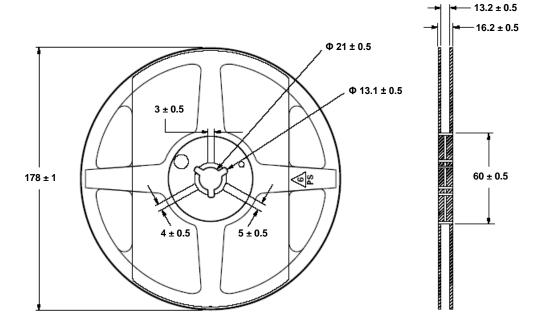
Notes:

- 1. Drawing not to scale.
- 2. All dimensions are in millimeters.
- 3. Unless otherwise indicated, tolerances are \pm 0.1mm.



Emitter Reel Packaging





Notes

- 1. Empty component pockets sealed with top cover tape.
- 2. 500 pieces per reel.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.



Precaution for Use

Storage

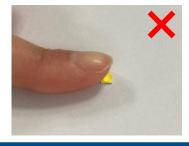
Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30 °C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.

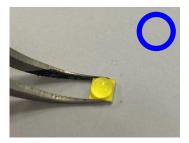
- The slug is is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets. http://www.prolightopto.com/

Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 0.3kgf impact or pressure on the silicone lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the silicone lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone lens must be prevented.
- Please do not mold over the silicone lens with another resin. (epoxy, urethane, etc)







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